

1. A method comprising:
    2. positioning a wafer between a pair of rotating
    3. brushes; and
    4. providing a cleaning solution through at least
    5. one of said brushes.
  1. 2. The method of claim 1 including providing a
  2. cleaning solution through the center of each of said
  3. brushes.
  1. 3. The method of claim 1 wherein providing a
  2. cleaning solution includes providing a solution of
  3. deionized water and a cleaning chemical.
  1. 4. The method of claim 1 including spraying a
  2. solution at the interface between said rotating brushes and
  3. said wafer.
  1. 5. The method of claim 4 including using a spray bar
  2. to spray the solution.
  1. 6. The method of claim 5 including spraying the
  2. deionized water at the interface between the brushes and
  3. wafers.

1       7. The method of claim 1 including providing the  
2 cleaning solution to both of said brushes.

1       8. The method of claim 1 including cleaning wafers  
2 after chemical mechanical polishing.

1       9. An apparatus comprising:  
2              a pair of rotatable brushes to receive a wafer  
3 between said brushes; and  
4              a cleaning solution dispenser to dispense  
5 cleaning solution from the interior of said brushes and to  
6 flow outwardly through the brushes to the brush wafer  
7 interface.

1       10. The apparatus of claim 9 including spray bars to  
2 spray liquid at the brush wafer interface.

1       11. The apparatus of claim 10 wherein said spray bars  
2 are coupled to a source of deionized water.

1       12. The apparatus of claim 9 including a reservoir to  
2 supply a source of cleaning solution.

1       13. The apparatus of claim 12 including a mixer to  
2 mix deionized water and a cleaning chemical to form the  
3 cleaning solution.

1        14. The apparatus of claim 9 including a pipe that  
2 provides a cleaning solution to the center of each of said  
3 brushes and ejects said cleaning solution radially  
4 outwardly through said brushes.

1        15. An apparatus for cleaning semiconductor wafers  
2 after chemical mechanical polishing comprising:  
3              a pair of counter-rotating brushes to receive a  
4 wafer to be cleaned between said brushes;  
5              a pair of spray bars to spray deionized water at  
6 the brush wafer interface; and  
7              a cleaning solution dispenser to dispense  
8 cleaning solution from the center of each of said brushes  
9 to flow outwardly through the brushes to the brush wafer  
10 interface.

1        16. The apparatus of claim 15 including a mixer to  
2 mix deionized water and a cleaning chemical to form a  
3 cleaning solution.

1        17. The apparatus of claim 15 including a pipe that  
2 extends through each of said brushes to dispense the  
3 cleaning solution from the center of said brushes.